xLED

xLED-LUN-8030 Pin Fin LED Heat Sink Φ80mm for Luminus

Features VS Benefits

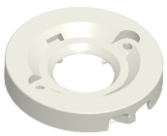
* The xLED-LUN-8030 Luminus Pin Fin LED Heat Sinks are specifically designed for luminaires using the Luminus LED engines.
* Mechanical compatibility with direct mounting of the LED engines to the LED cooler and thermal performance matching the lumen packages.
* For spotlight and downlight designs from 1,000 to 2,600 lumen.
* Thermal resistance range Rth 3.13°C/W.
* Modular design with mounting holes foreseen for direct mounting of Luminus COB series.
* Diameter 80mm - standard height 30mm, Other heights on request.
* Forged from highly conductive aluminum.

Zhaga LED engine and radiator assembly is a unified future international standardization

* Below you find an overview of Luminus COB's and LED modules which standard fit on the Pin Fin LED Heat Sinks.
* In this way mechanical after work and related costs can be avoided, and lighting designers can standardize their designs on a limited number of LED Pin Fin LED Heat Sink.

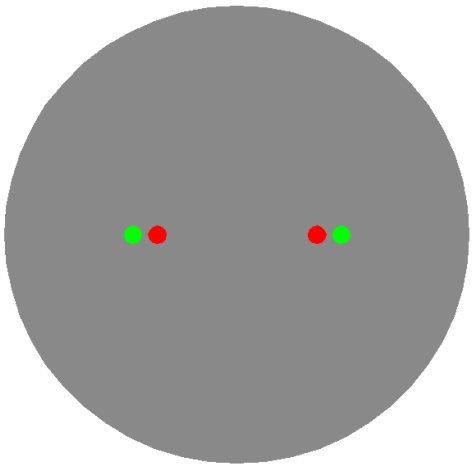
LUMINUS

BJB



TE connectivity

LEDiL



Luminus LED Modules directly Mounting Options

Luminus COB series.

CXM-11-AC;
CIM/CLM/CXM-14;
With the Zhaga Book 3 holders for the green indicator marks.
TE Connectivity Holder: 2213254-1;
BJB Holder:47.319.2021.50;
Without the holders for the red indicator marks.
Direct mounting with machine screws M3x6.5mm.
With the LEDiL products:
Lena series: CN12xxx;
Lenina series: CN12xxx; C12xxx;

Luminus COB series.

CXM-18;
With the Zhaga Book 3 holders for the green indicator marks.
TE Connectivity Holder: 2213258-1;
BJB Holder:47.319.2280.50;
Direct mounting with machine screws M3x6.5mm.
With the LEDiL products:
Lena series: CN12xxx;

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Mounting Options and Drawings & Dimensions

Example:xLED-LUN-8030-B-1,2

Example:xLED-LUN-80 1 - 2 - 3

1 **Height (mm)**

2 **Anodising Color**

B-Black

C-Clear

Z-Custom

3 **Mounting Options - see graphics for details Combinations available**

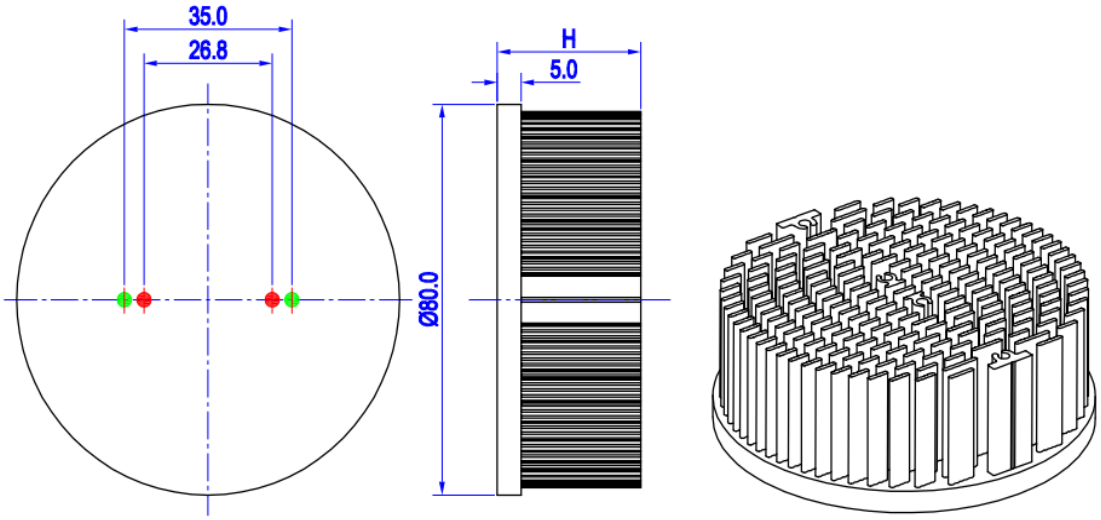
Ex.order code - 12

means option 1 and 2 combined

Notes:

- Mentioned models are an extraction of full product range.
- For specific mechanical adaptations please contact MingfaTech.
- MingfaTech reserves the right to change products or specifications without prior notice.

MOUNTING OPTION	Module type	Holder NO.	LEDiL products		THREAD	THREAD DEPTH	THREAD HOLE DISTANCE
			Lenina Series	Lena series			
1	CXM-11; CIM/CLM/CXM-14	/	CN12xxx; C12xxx;	CN12xxx;	M3	6.5mm	26.8mm/ 2-@180°
2	CXM-11; CIM/CLM/CXM-14	BJB Holder 47.319.2021.50	CN12xxx; C12xxx;	CN12xxx;	M3	6.5mm	35.0mm/ 2-@180° (Zhaga book 3)
2	CXM-11; CIM/CLM/CXM-14	TE Holder 2213254-1	CN12xxx; C12xxx;	CN12xxx;	M3	6.5mm	35.0mm/ 2-@180° (Zhaga book 3)
2	CXM-18;	BJB Holder 47.319.2280.50	/	CN12xxx;	M3	6.5mm	35.0mm/ 2-@180° (Zhaga book 3)
2	CXM-18;	TE Holder 2213258-1	/	CN12xxx;	M3	6.5mm	35.0mm/ 2-@180° (Zhaga book 3)



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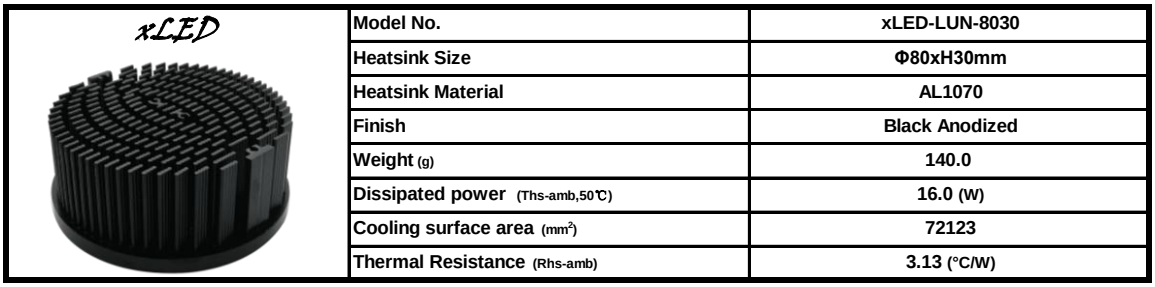
The product deta table



Model No.	xLED-LUN-8030
Heatsink Size	Φ80xH30mm
Heatsink Material	AL1070
Finish	Black Anodized
Weight (g)	140.0
Dissipated power (Ths-amb,50℃)	16.0 (W)
Cooling surface area (mm^2)	72123
Thermal Resistance (Rhs-amb)	3.13 (°C/W)

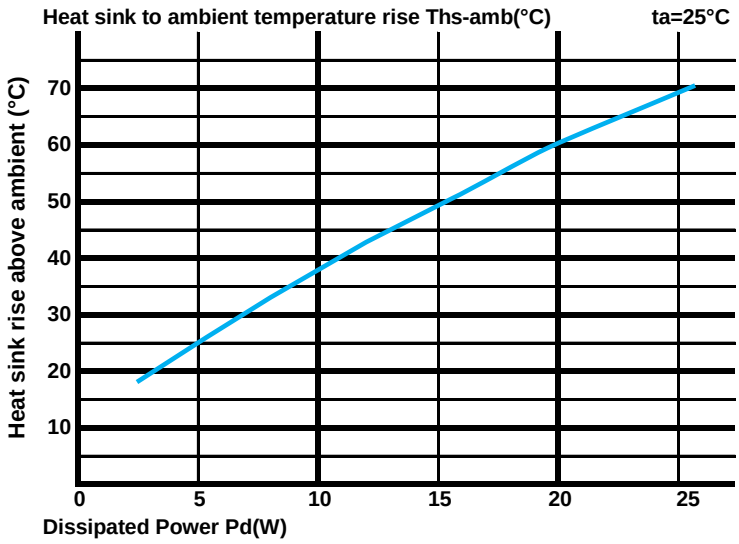
The thermal data table

* Please be aware the dissipated power Pd is not the same as the electrical power Pe of a LED module.

*To calculate the dissipated power please use the following formula: Pd = Pe x (1-ηL).

Pd - Dissipated power ; Pe - Electrical power ; ηL = Light effciency of the LED module;

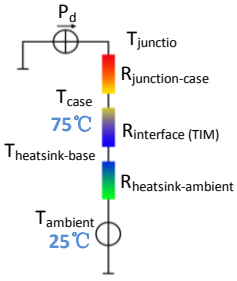
Pd = Pe x (1-ηL)		Heat sink to ambient thermal resistance Rhs-amb (°C/W)	Heat sink to ambient temperature rise Ths-amb (°C)
		xLED-LUN-8030	
Dissipated Power Pd(W)	5.0	5.00	25.0
	10.0	3.80	38.0
	15.0	3.27	49.0
	20.0	3.00	60.0
	25.0	2.76	69.0



*The aluminum substrate side of the package outer shell is thermally connected to the heat sink via TIM (Thermal interface material).

MingFa recommends the use of a high thermal conductive interface between the LED module and the LED cooler.

Either thermal grease,A thermal pad or a phase change thermal pad thickness 0.1-0.15mm is recommended.



*Thermal resistance is a heat property and a measurement of a temperature difference by which an object or material resists a heat flow. Geometric shapes are different, the thermal resistance is different. Formula: θ =(Ths−Ta)/Pd

θ - Thermal Resistance [°C/W] ; Ths - Heatsink temperature ; Ta - Ambient temperature ;

*The thermal resistance between the junction section of the light-emitting diode and the aluminum substrate side of the package outer shell is $R_{junction-case}$, the thermal resistance of the TIM outside the package is $R_{interface\ (TIM)}$ [°C/W], the thermal resistance with the heat sink is $R_{heatsink-ambient}$ [°C/W], and the ambient temperature is $T_{ambient}$ [°C].

*Thermal resistances outside the package $R_{interface\ (TIM)}$ and $R_{heatsink-ambient}$ can be integrated into the thermal resistance $R_{case-ambient}$ at this point.Thus, the following formula is also used:

$T_{junction}=(R_{junction-case}+R_{case-ambient})\cdot Pd+T_{ambient}$

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